

## -30V P-Channel Enhancement Mode MOSFET

### Description

The AP70P03P/T uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -30V$   $I_D = -78A$

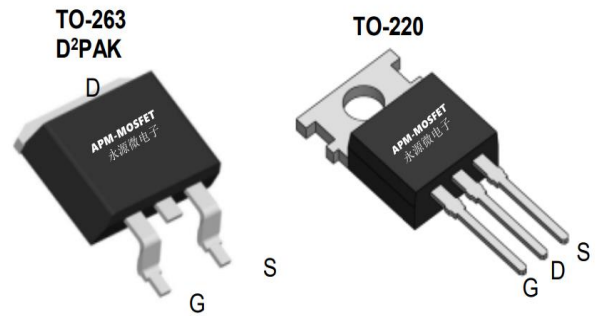
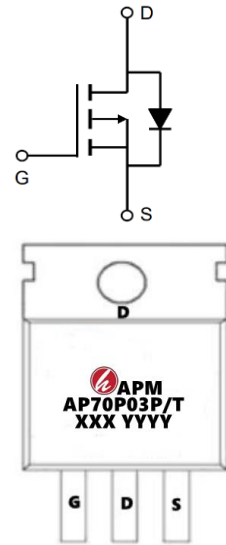
$R_{DS(ON)} < 13m\Omega$  @  $V_{GS} = -10V$  (Type: 8.8m $\Omega$ )

### Application

Lithium battery protection

Wireless impact

Mobile phone fast charging



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP70P03P	TO-220-3L	AP70P03P XXX YYYY	1000
AP70P03T	TO-263-3L	AP70P03T XXX YYYY	800

### Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_{D@TC=25^\circ C}$	Continuous Drain Current, $V_{GS} @ -10V_1$	-78	A
$I_{D@TC=100^\circ C}$	Continuous Drain Current, $V_{GS} @ -10V_1$	-57	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-130	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	125	mJ
$I_{AS}$	Avalanche Current	-50	A
$P_{D@TC=25^\circ C}$	Total Power Dissipation <sup>4</sup>	37	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient 1	62.5	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	3.36	$^\circ C/W$

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### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

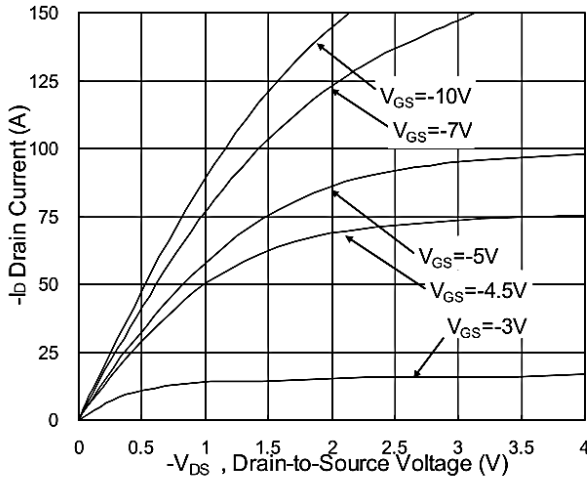
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=-250\mu A$	-30	-34	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1mA$	---	-0.0232	---	V/ $^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance	$V_{GS}=-10V$ , $I_D=-30A$	---	8.8	13	m $\Omega$
		$V_{GS}=-4.5V$ , $I_D=-15A$	---	14	20	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu A$	-1.2	-1.4	-2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	4.6	---	mV/ $^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-24V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu A$
		$V_{DS}=-24V$ , $V_{GS}=0V$ , $T_J=55^\circ\text{C}$	---	---	-5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=-5V$ , $I_D=-30A$	---	30	---	S
$R_g$	Gate Resistance	$V_{DS}=0V$ , $V_{GS}=0V$ , $f=1MHz$	---	9	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-15V$ , $V_{GS}=-4.5V$ , $I_D=-15A$	---	22	---	nC
$Q_{gs}$	Gate-Source Charge		---	8.7	---	
$Q_{gd}$	Gate-Drain Charge		---	7.2	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-15V$ , $V_{GS}=-10V$ , $R_G=3.3\Omega$ $I_D=-15A$	---	8	---	ns
$T_r$	Rise Time		---	73.7	---	
Td(off)	Turn-Off Delay Time		---	61.8	---	
$T_f$	Fall Time		---	24.4	---	
Ciss	Input Capacitance	$V_{DS}=-15V$ , $V_{GS}=0V$ , $f=1MHz$	---	2215	---	pF
Coss	Output Capacitance		---	310	---	
Crss	Reverse Transfer Capacitance		---	237	---	
IS	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-42	A
ISM	Pulsed Source Current		---	---	-130	A
VSD	Diode Forward Voltage	$V_{GS}=0V$ , $I_S=-1A$ , $T_J=25^\circ\text{C}$	---	---	-1	V
trr	Reverse Recovery Time	$I_F=-15A$ , $dI/dt=100A/\mu s$ , $T_J=25^\circ\text{C}$	---	19	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	9	---	nC

#### Note :

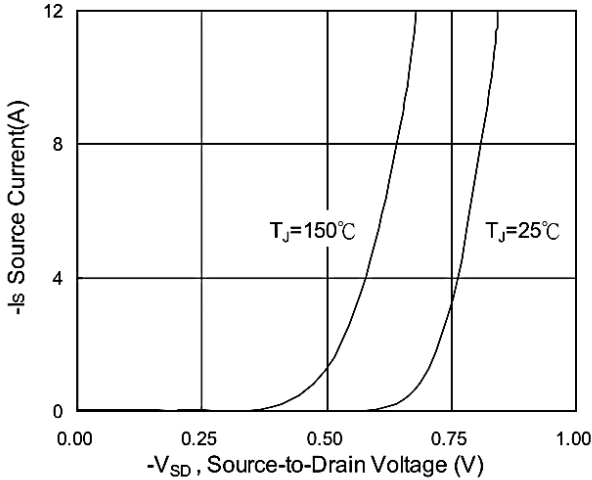
- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 20Z copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
- 4、EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=-24V$ ,  $V_G=-10V$ ,  $R_G=7\Omega$ ,  $L=0.1mH$ ,  $I_{AS}=-50A$
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

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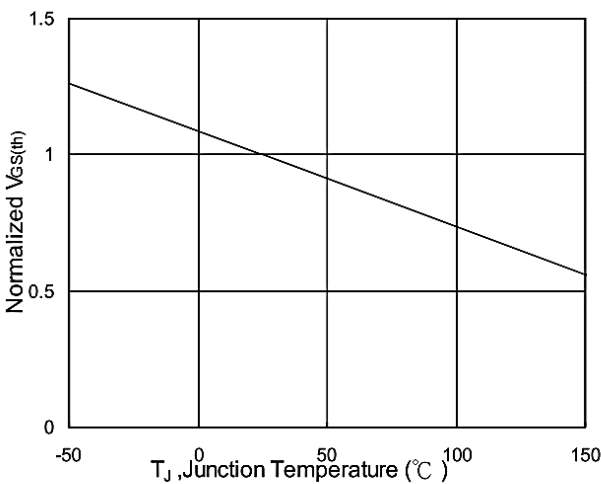
### Typical Characteristics



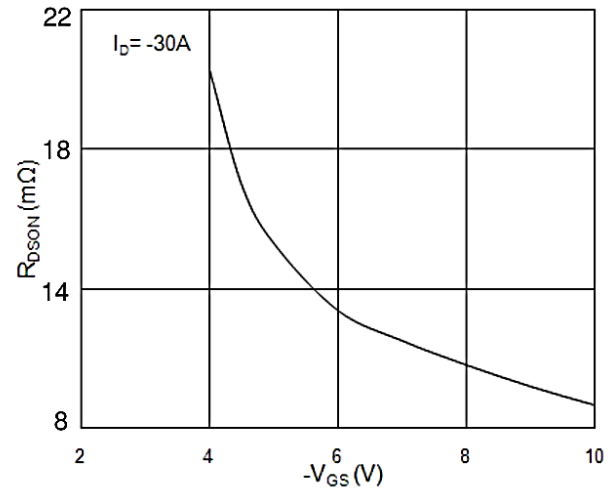
**Fig.1 Typical Output Characteristics**



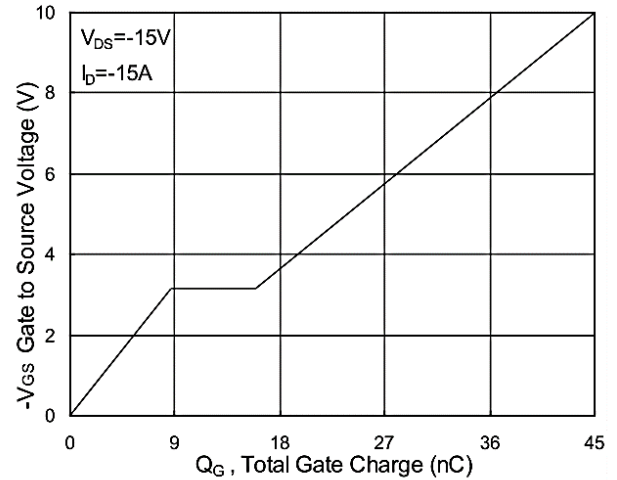
**Fig.3 Forward Characteristics of Reverse**



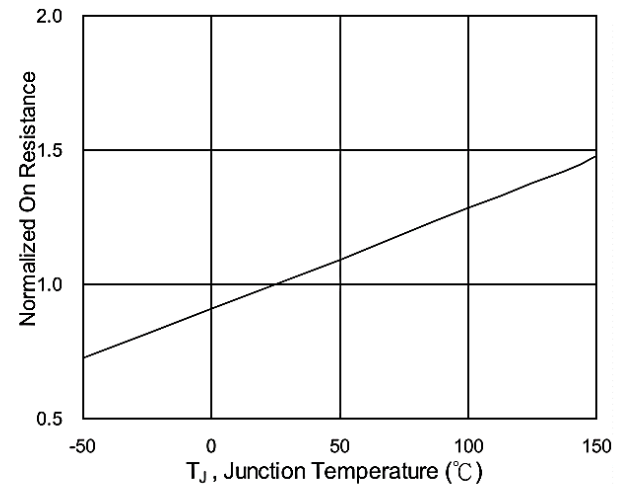
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.2 On-Resistance vs. G-S Voltage**

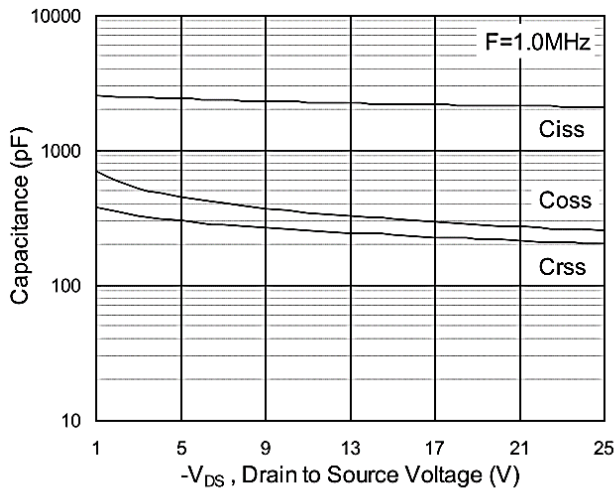


**Fig.4 Gate-Charge Characteristics**

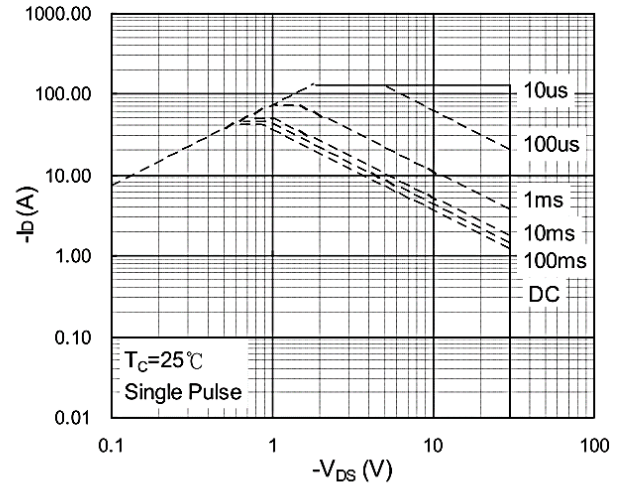


**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

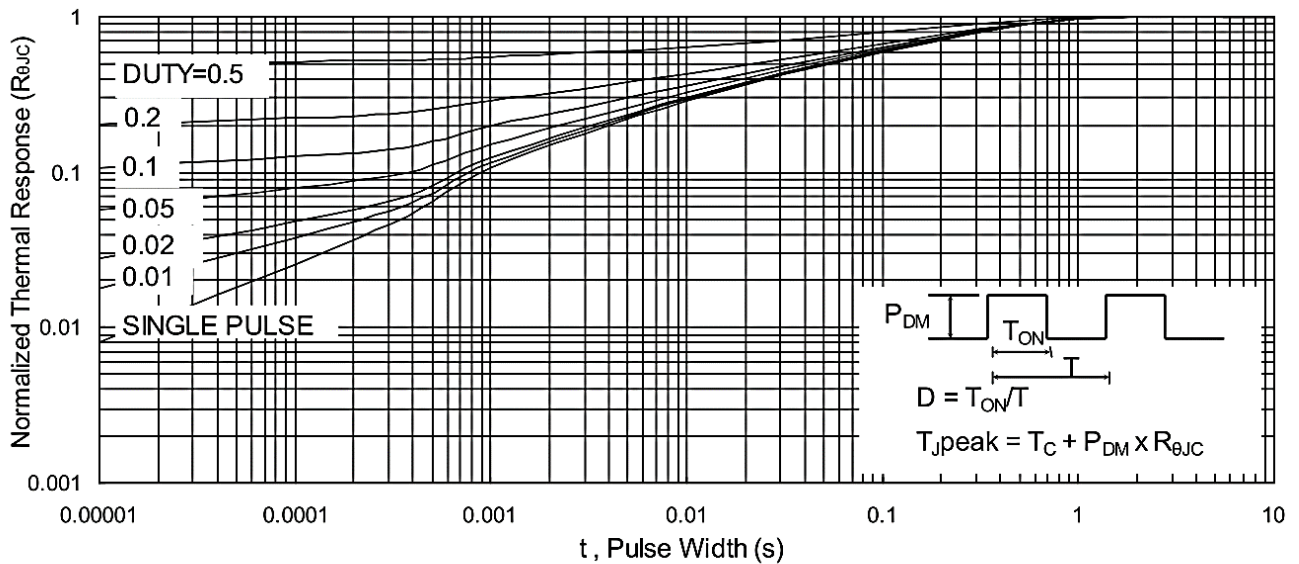
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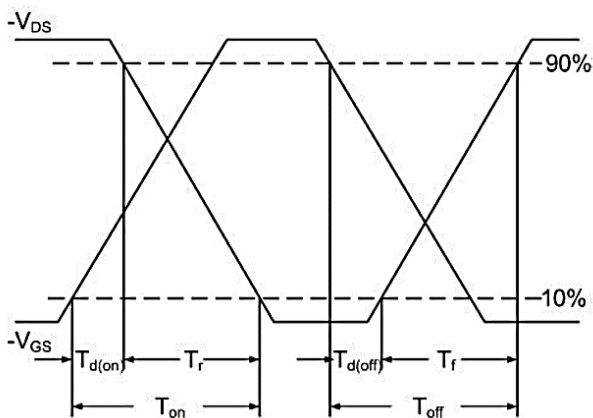
**Fig.7 Capacitance**



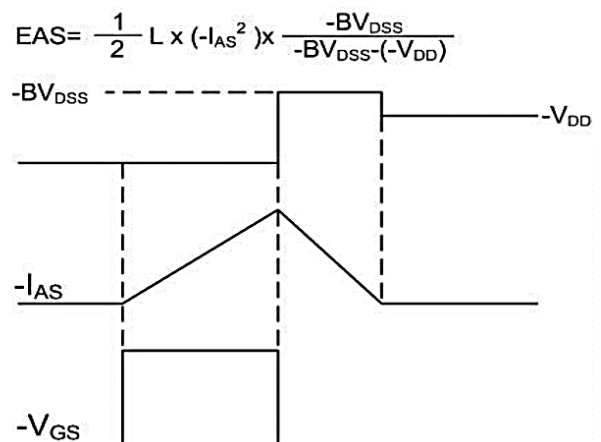
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



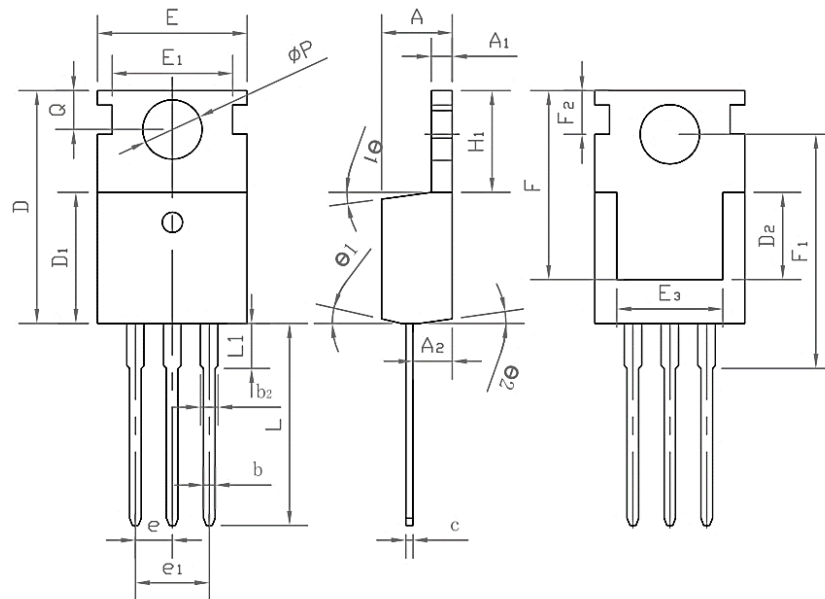
**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

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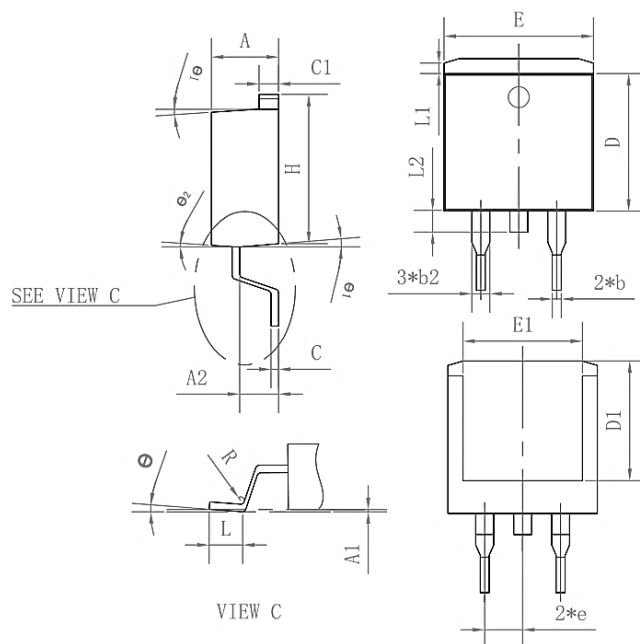
**Package Mechanical Data-TO-220-3L-SLK**



Symbol	Common		
	mm		
	Mim	Nom	Max
A	4.27	4.57	4.87
A1	1.15	1.30	1.45
A2	2.10	2.40	2.70
b	0.70	0.80	1.00
b2	1.17	1.27	1.50
D	0.40	0.50	0.65
D1	8.80	9.10	9.40
D2	5.70	6.70	7.00
E	9.70	10.00	10.30
E1	-	8.70	-
E2	9.63	10.00	10.35
E3	7.00	8.00	8.40
e	0.37		
e1	0.10		
H1	6.00	6.50	6.85
L	12.75	13.50	13.90
L1	-	3.10	3.40
$\Phi p$	3.45	3.60	3.75
Q	2.60	2.80	3.00
$\theta_1$	4°	7°	10°
$\theta_2$	0°	3°	6°
F	13.30	13.50	13.70
F1	15.50	15.90	16.30
F2	2.80	3.00	3.20

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**Package Mechanical Data-TO-263-3L-SLK**



Symbol	Common		
	mm		
	Mim	Nom	Max
A	4.35	4.47	4.60
A1	0.09	0.10	0.11
A2	2.30	2.40	2.70
b	0.70	0.80	1.00
b2	1.25	1.36	1.50
C	0.45	0.50	0.65
C1	1.29	1.30	9.40
D	9.10	9.20	9.30
D1	7.90	8.00	8.10
E	9.85	10.00	10.20
E1	7.90	8.00	8.10
H	15.30	15.50	15.70
e	-	2.54	-
L	2.34	2.54	2.74
L1	1.00	1.10	1.20
L2	1.30	1.40	1.50
R	0.24	0.25	0.26
theta	0°	4°	8°
theta_1	4°	7°	10°
theta_2	0°	3°	6°

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Edition	Date	Change
Rev1.0	2022/3/10	Initial release

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